VETERANS OF FOREIGN WARS

VFW Post # 8870 Freedom Scholarship

VFW Post # 8870, Edmonds, sponsors the Freedom Scholarship for four deserving seniors who will be enrolling full time in an accredited vocational, technical, college or university in the fall semester. The $1500 scholarship shall be paid directly to the student's school account to help defray tuition costs, fees, and expenses.

Applicant's Name _____ Date of Birth_____

Address _____City_____State _____Zip _____

Phone _____E-mail_____Social Security #_____

School District in Which You Reside (Circle One) Edmonds Mukilteo

Name of college/trade school you plan to attend in the fall and the address for the Bursar's Office:

Name of School _____

Address _____City_____State _____Zip _____

The following materials must accompany the Freedom Scholarship application form:

- A high school transcript that includes grades from your junior and senior years;
- A resume that includes the school sponsored activities in which you have participated during your high school years, leadership positions, jobs you have held, and service related activities for which you have volunteered; and
- An essay that is typed and from 300 to 500 words in which you explain:
    1. What freedom means to you; and
    2. How our Constitution establishes and maintains a culture of freedom in our country.
- (Optional) Name of parents and/or grandparents that are military veterans

We, the undersigned, give our permission for the VFW Post #8870 Edmonds to receive and review a copy of the applicant's high school transcript. We understand that the members of the Post's Scholarship Committee shall review all application materials and Committee decisions regarding the awarding of the Freedom Scholarship shall be final.

_____

Applicant's Signature Print Name Date

_____

Parent's Signature Print Name Date

Please forward the completed application and all supporting materials to:

Mail: Scholarship Committee
VFW Post # 8870
PO Box 701
Edmonds, WA 98020

Or

E-Mail: scholarships@vfw8870.org

DEADLINE FOR SUBMISSION OF APPLICATION MATERIALS IS APRIL 15